



PATENT
Docket No.: 1133/201

CERTIFICATE OF MAILING OR TRANSMISSION

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Julie Nguyen

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the application of:

Kahner, et al.

Serial No.: 10/676,908

Filing Date: September 30, 2003

For: ABATEMENT OF CONTAMINATION
PRESENT IN STRUCTURES

Examiner: Joyner, Kevin

Group Art Unit: 1744

DECLARATION OF PHILIP GRAVES

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

I, PHILIP GRAVES, declare as follows:

1. I am a member of the State Bar of California in good standing (California State Bar No. 153441).

2. I am the President of Innovative Mold Solutions, LLC ("IMS"), the current Assignee of the above-captioned U.S. patent application ("Patent Application").

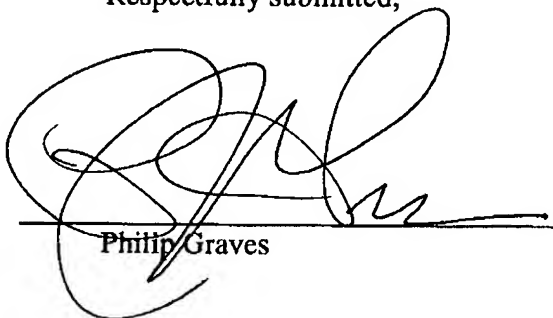
3. Prior to October 8, 2002, I was in discussions with Alfred A. Kahner, III; Stephen W. Roy; and James L. Unmack, the joint inventors of the Patent Application, concerning exploitation of the subject matter of the Patent Application.

4. On September 30, 2002, I received an email delivered to my former work email address pgraves@linerlaw.com (alias "PGRAVES") from Stephen Roy (one of the co-inventors of the Patent Application) with an attachment of a one-page written disclosure of a certain aspect of the subject matter of Patent Application. On October 1, 2002, I forwarded from my former work email address the September 30 email along with the attachment to my alternate home email address pjg100@earthlink.net (alias "Philip Graves (Email 2)". Attached as Exhibit A is a true copy of a printout of the October 1 email, which shows the thread of emails originating from Stephen Roy, and as Exhibit B a true copy of a printout of the attachment received with the September 30 email.

I declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed by me to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the Patent Application or any patent issued thereon.

Executed this 13 day of January, 2008 at Los Angeles, California.

Respectfully submitted,



Philip Graves

Attachments:

Exhibit A

Exhibit B

Wen Liu

From: PGRAVES [PGRAVES@linerlaw.com]
Sent: Tuesday, October 01, 2002 8:47 PM
To: Philip Graves (E-mail 2)
Subject: FW: Patent
Attachments: Patent.doc

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Liner Yankelevitz Sunshine & Regenstreif LLP
3130 Wilshire Boulevard
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Santa Monica, California 90403
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-----Original Message-----

From: Process [mailto:process@attbi.com]
Sent: Monday, September 30, 2002 4:51 AM
To: PGRAVES
Subject: FW: Patent

-----Original Message-----

From: Process [mailto:process@attbi.com]
Sent: Monday, September 30, 2002 3:49 AM
To: Phil Graves - Home
Subject: Patent

<<...>>

Phil,

When all was said and done we have two concepts. We don't know if both can be put on one patent.

Attached you will find one of these.

Regards,

Stephen Roy

EXHIBIT " A "

September 30, 2002

A novel method for control of mold infections in voids in structures utilizing microwave energy and adhesives.

Current methodologies require complete removal of infected materials such as drywall to eliminate mold in infected structures. This requires engineered isolation techniques to prevent inadvertent dispersal of mold spores or volatile organic compounds. The current methods are expensive and disruptive for both owners and tenants.

This method involves first heating, in situ, the suspect or identified moldy area with a directed beam of microwave energy to kill the active mold. The energy is applied to the microwave device after a small hole or holes have been made adjacent to the moldy area and a HEPA vacuum has been attached and the vacuum has been started to create a negative air condition in the void. The HEPA vacuum is utilized to remove any sporation or voc's that are released when the microwave begins to heat the mold infected area.

After sufficient temperature to kill the mold has been applied to the area an adhesive is applied by spray, foam or fogging the interior of the wall void through the hole or holes previously made. This adhesive acts to bond any spores still remaining in the void to the existing surfaces thereby minimizing future spore release and the attendant allergen potential.

James Unmack
Alfred Kahner
Stephen Roy

EXHIBIT " B "